

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ0904NSI	**Issued**	03. June 2021
MA#	MA005421889		
Package	PG-TSDSON-8-25	**Weight***	35.44 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.303	0.86	0.86	8564	8564
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		69	
	non noble metal	zinc	7440-66-6	0.010	0.03		278	
	non noble metal	iron	7439-89-6	0.197	0.56		5552	
	non noble metal	copper	7440-50-8	7.988	22.54	23.14	225415	231314
wire	noble metal	gold	7440-57-5	0.029	0.08	0.08	824	824
encapsulation	organic material	carbon black	1333-86-4	0.038	0.11		1075	
	plastics	epoxy resin	-	1.963	5.54		55385	
	inorganic material	silicondioxide	60676-86-0	17.055	48.10	53.75	481261	537721
leadfinish	non noble metal	tin	7440-31-5	0.395	1.12	1.12	11154	11154
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	573	573
solder	non noble metal	tin	7440-31-5	0.010	0.03		273	
	noble metal	silver	7440-22-4	0.012	0.03		342	
	non noble metal	lead	7439-92-1	0.463	1.31	1.37	13054	13669
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			26	
	non noble metal	zinc	7440-66-6	0.004	0.01		103	
	non noble metal	iron	7439-89-6	0.073	0.21		2056	
	non noble metal	copper	7440-50-8	2.959	8.35	8.57	83501	85686
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			33	
	non noble metal	zinc	7440-66-6	0.005	0.01		133	
	non noble metal	iron	7439-89-6	0.094	0.27		2652	
	non noble metal	copper	7440-50-8	3.816	10.77	11.05	107677	110495
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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